

#### **Features**

- Peak Output Current : IOP = ±2.5A (max)
- Threshold Input Current: IFLH = 5 mA (max)
- Common mode transient immunity : ±20kV/µs (min )
- Under voltage lock out (UVLO) protection with hysteresis
- Pb free and RoHS compliant.
- Regulatory Approvals
  - UL UL1577 (E364000)
  - VDE EN60747-5-5(VDE0884-5)
  - CQC GB4943.1, GB8898
  - IEC60065, IEC60950

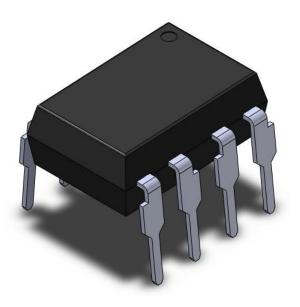
#### **Description**

The CT3120 consists of a GaAsP LED optically coupled to an integrated circuit with a power output stage. This optocoupler is ideally suited for driving power IGBTs and MOSFETs used in motor control inverter applications. The high operating voltage range of the output stage provides the drive voltages required by gate controlled devices.

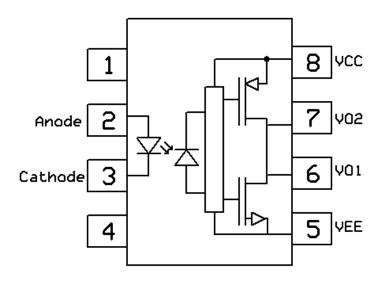
#### **Applications**

- Isolated IGBT/Power MOSFET gate drive
- Industrial Inverter
- AC brushless and DC motor drives
- Induction Heating

### **Package Outline**



#### **Schematic**



Note: Different lead forming options available. See package dimension.



#### **Truth Table**

LED	Vcc-V <sub>EE</sub> Positive Going	Vcc-V <sub>EE</sub> Negative Going	Output
Off	0 to 30 V	0 to 30V	Low
On	0 to 11.5V	0 to 10V	Low
On	11.5 to 13.5V	10 to 12V	Transition
On	13.5 to 30V	12 to 30V	High

### Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage	5000	V <sub>RMS</sub>	1
Topr	Operating temperature	-40 ~ +100	°C	
Tstg	Storage temperature	-55 ~ +125	°C	
TsoL	Soldering temperature	260	°C	2
PT	Total Power Dissipation	300	mW	
fopr	Operating Frequency	50	kHz	3
Emitter				
l <sub>F</sub>	Forward current	25	mA	
I <sub>FP</sub>	Peak forward current (50% duty, 1ms P.W)	1	Α	
V <sub>R</sub>	Reverse voltage	5	٧	
Detector				
P <sub>D</sub>	Power dissipation	250	mW	
V <sub>O(PEAK)</sub>	Peak Output Voltage	35	V	
Іорн	Output High Peak Current	2.5	Α	4
I <sub>OPL</sub>	Output Low Peak Current	2.5	Α	4
Vcc	Supply voltage	0 to 30	V	

#### Notes

- 1. AC for 1 minute,  $RH = 40 \sim 60\%$ .
- 2. For 10 second peak
- 3. Exponential Waveform, IO(PEAK)  $\leq$  |2.5A|, Pulse Width  $\leq$  0.3us
- 4. Pulse Width = 10uS, DC = 1.0%



#### **Electrical Characteristics**

Typical values are measured at Vcc=30V,  $V_{EE}$ = Gnd,  $T_A$  = 25°C(unless otherwise stated)

#### **Emitter Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	IF = 10mA	-	1.45	1.7	V	
VR	Reverse Voltage	IR = 10μA	5.0	-	-	V	
ΔV <sub>F</sub> /ΔT <sub>A</sub>	Temperature coefficient of forward voltage	IF =10mA	-	-1.8	-	mV/°C	

#### **Detector Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
Iccl	Logic Low Supply Current	$V_F = 0$ to 0.8V, $V_O = Open$	-	1.5	3.7	mA	
Іссн	Logic High Supply Current	I <sub>F</sub> = 7mA to 10mA, V <sub>O</sub> = Open	-	1.7	3.7		

#### **Transfer Characteristics**

Symbol	Parameters	Test Conditions	Min	Тур	Мах	Units	Notes
		I <sub>F</sub> = 10mA, I <sub>O</sub> = -2.5A	V <sub>CC</sub> -6.2	-	-		
Vон	V <sub>OH</sub> High Level Output Voltage	I <sub>F</sub> = 10mA, I <sub>O</sub> = -100mA	Vcc-0.2	_	-	V	
		·	5				
		I <sub>F</sub> = 0mA, I <sub>O</sub> = 2.5A	-	-	V <sub>EE</sub>		
Vol	Low Level Output Voltage				+6.25	· V	
	, ,	I <sub>F</sub> = 0mA, I <sub>O</sub> = 100mA	-	-	V <sub>EE</sub>		
					+0.25		
I <sub>OPH</sub>	High Level Output Current	Vo= Vcc-3V	-1	-	-	A	
ЮРН	Trigit Level Output Outlett	Vo= Vcc-6V	-2	-	-	,,	
l	Low Lovel Output Current	Vo= VEE+3V	1	-	-	Α	
I <sub>OPL</sub>	Low Level Output Current	Vo= VEE+6V	2	-	-	A	
I <sub>FLH</sub>	Input Threshold Current	I <sub>O</sub> = 0mA, V <sub>O</sub> > 5V	-	2.0	5.0	mA	
V <sub>FHL</sub>	Input Threshold Voltage	Io= 0mA, Vo< 5V	0.8	-	-	V	
V <sub>UVLO+</sub>	Under Voltage Lockout	Io= 10mA, Vo> 5V 11 - 13.5		13.5	V		
V <sub>UVLO</sub> -	Threshold	Io= 10mA, Vo< 5V	10	-	12.2	V	



#### **Electrical Characteristics**

Typical values are measured at Vcc=30V,  $V_{EE}$ = Gnd,  $T_A$  = 25  $^{\circ}$ C(unless otherwise stated)

### **Switching Characteristics**

Symbol	Parameters	Test C	onditions	Min	Тур	Max	Units	Notes
T <sub>PHL</sub>	High to Low Propagation Delay			120	185	300	ns	
T <sub>PLH</sub>	Low to High Propagation Delay	1 74- 40	A O 40E D	150	175	300	ns	
Pwd	Pulse Width Distortion		A, C <sub>L</sub> = 10nF, R <sub>L</sub> =		10	100	ns	
tpsk	Propagation Delay Skew	- 10Ω, f= 10kHz, Duty = 50%, - T <sub>A</sub> = 25 <sup>0</sup> C				40	ns	
t <sub>r</sub>	Rise Time				60		ns	
<b>t</b> f	Fall Time				60		ns	
tuvlo(on)	UVLO Turn On Delay	I <sub>F</sub> = 10mA, V <sub>O</sub> > 5V			2.5		μs	
t <sub>UVLO(OFF)</sub>	UVLO Turn Off Delay	I <sub>F</sub> = 10mA, V <sub>0</sub>	o< 5V		0.4		μs	
CM <sub>H</sub>	Common Mode Transient High	Vcc= 30V, R <sub>L</sub> = 350Ω,	I <sub>F</sub> = 7 to 16mA,	-20			kV/μs	
CML	Common Mode Transient Low	T <sub>A</sub> = 25 <sup>0</sup> C, V <sub>CM</sub> = 2kV	I <sub>F</sub> = 0mA	20			kV/μs	



-4.0 -3.5

-2.5 -2.0

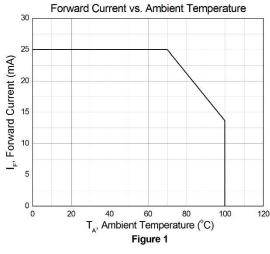
-1.0 -0.5

0.0 L 1E-3

K Factor (mV/°C)

# 2.5A MOSFET/IGBT Gate Driver Optocoupler

### **Typical Characteristic Curves**



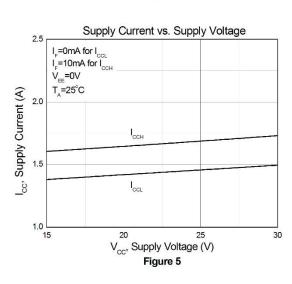
K Factor vs. Forward Current

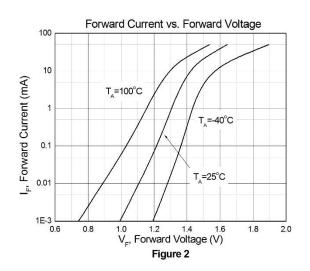
I<sub>F</sub>, Forward Current (mA)

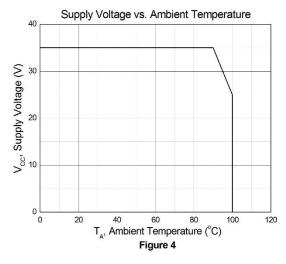
Figure 3

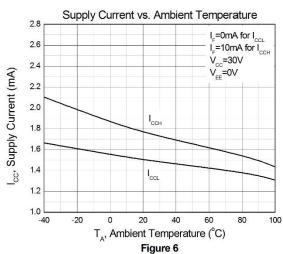


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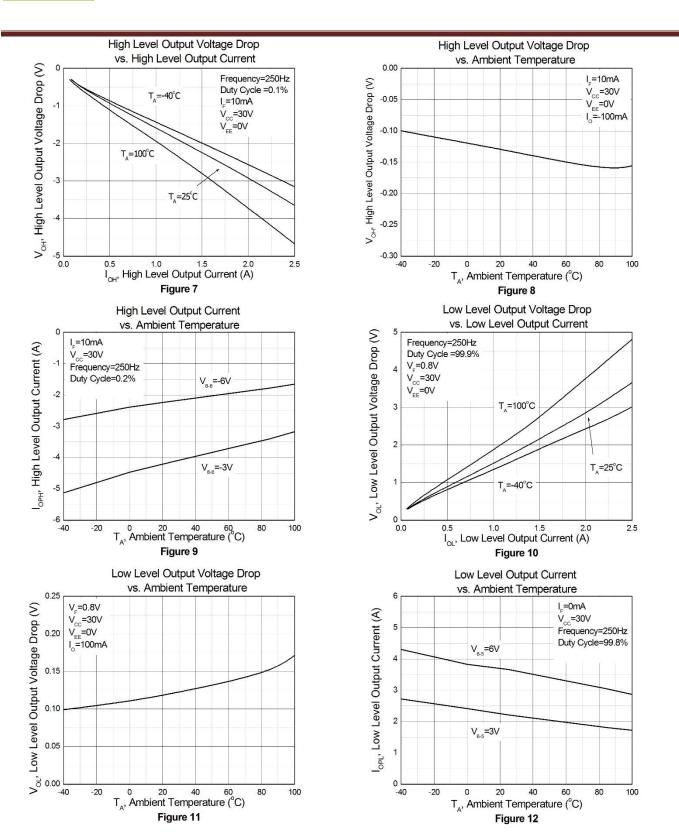




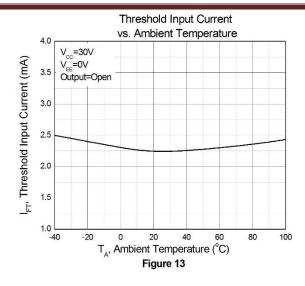


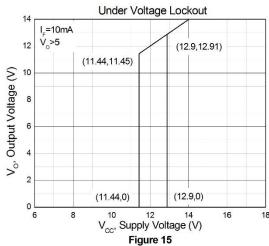


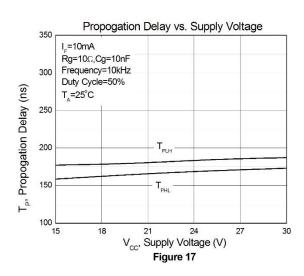


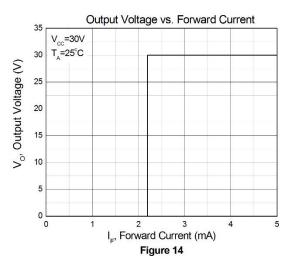


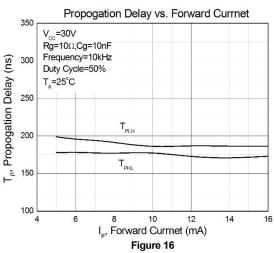


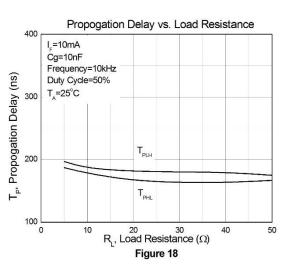






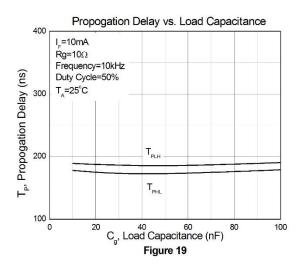


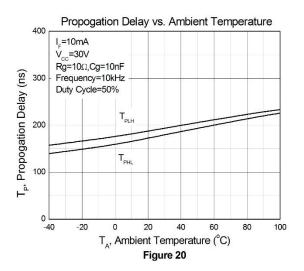








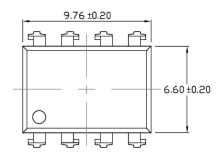


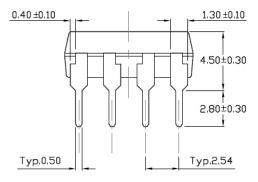


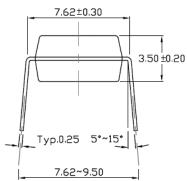


### Package Dimension Dimensions in mm unless otherwise stated

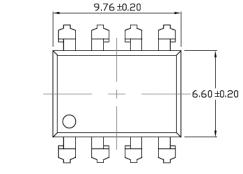
### Standard DIP - Through Hole

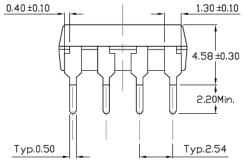


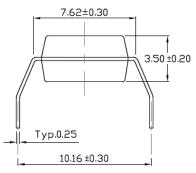




### Gullwing (400mil) Lead Forming – Through Hole (M Type)

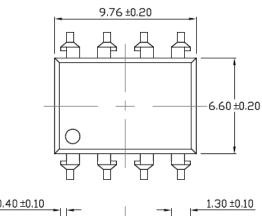


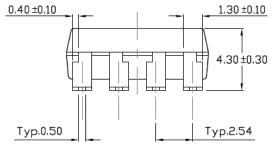


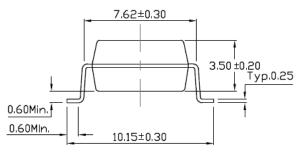




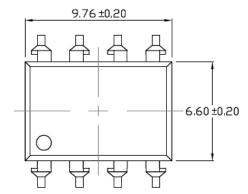
### **Surface Mount Lead Forming (S Type)**

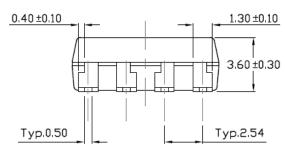


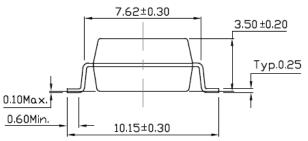




### **Surface Mount (Low Profile) Lead Forming (SL Type)**

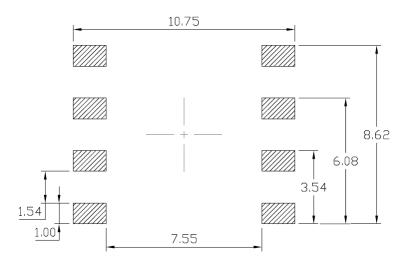




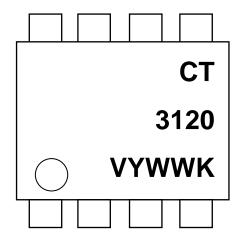




### Recommended Solder Mask Dimensions in mm unless otherwise stated



### **Device Marking**



#### Note:

CT : Denotes "CT Micro" 3120 : Product Number

V : VDE Option
Y : Fiscal Year
WW : Work Week

K : Production Code



### **Ordering Information**

# CT3120(Y)(Z)

Y = Lead form option (S, SL, M or none)

Z = Tape and reel option (T1, T2 or none)

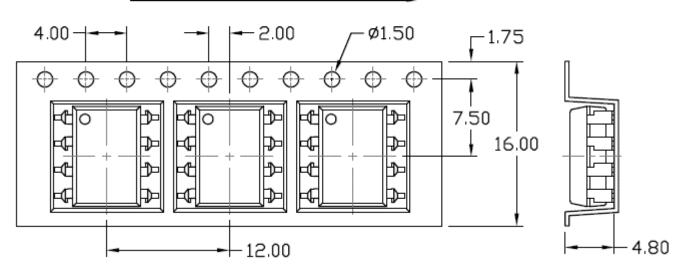
Option	Description	Quantity
None	Standard 8 Pin Dip	40 Units/Tube
M	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	1000 Units/Reel



### Carrier Tape Specifications Dimensions in mm unless otherwise stated

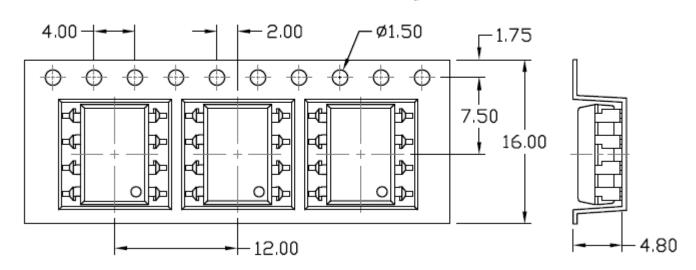
### Option S(T1) & SL(T1)

# Input Direction



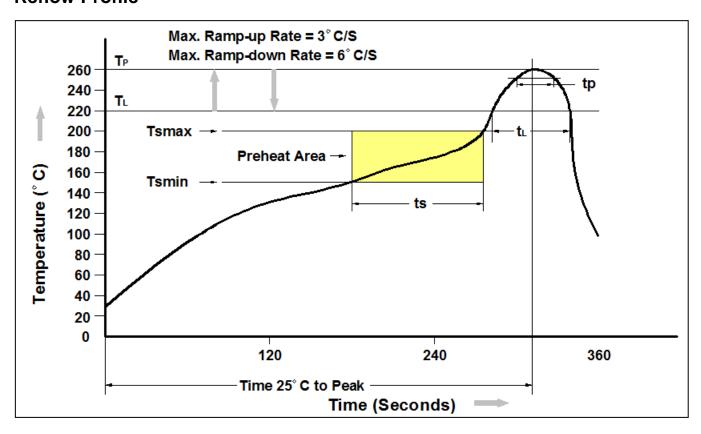
### Option S(T2) & SL(T2)

# Input Direction





#### **Reflow Profile**



Profile Feature	Pb-Free Assembly Profile	
Temperature Min. (Tsmin)	150°C	
Temperature Max. (Tsmax)	200°C	
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	
Ramp-up Rate (t∟ to t⊳)	3°C/second max.	
Liquidous Temperature (T <sub>L</sub> )	217°C	
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds	
Peak Body Package Temperature	260°C +0°C / -5°C	
Time (t <sub>P</sub> ) within 5°C of 260°C	0°C 30 seconds	
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max	
Time 25°C to Peak Temperature	8 minutes max.	



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